

封装类型 Package Type

Package Code	Package Type
D	DFN8X8
DA	DFN5X6 (Drain as pin1)
DC	DFN5X6 (Source as pin1)
DE	DFN3X3
SC	SOT223
SD	SOP8
SE	TSSOP14
SH	EN-SOP15
QA	QFN6X8-30
QH	QFN6X8-32
TA	TOLL
TH	TO220
TJ	TO220F
TK	TO252-3
TM	TO252-4L
TD	TO247-4L
TQ	V-QDPAK
TS	S-QDPAK
TP	TOLT (Drain as pin1)
TR	TOLT (Source as pin1)
FQ	FCQFN
EQ	EN-FCQFN (Enhanced heat dissipation FCQFN)
LA	FCLGA
EX	En-FCLGA (Enhanced heat dissipation FCLGA , Source down, " X" varies with PKG size)
EXD	En-FCLGA (Enhanced heat dissipation FCLGA , Drain down, " X" varies with PKG size)
W	WLCSP
N	Bumping + CP wafer (LV/MV Single GaN & VGaN)
N	CP wafer (HV Single GaN & VGaN)
R	Fab out wafer (LV/MV/HV Single GaN & VGaN)
NS	CP wafer (HV Sense GaN)

HV//MV/LV/VGaN

INN

Innoscience

VVV

Drain Voltage Rating

PP

Package Code

RRR

Max Ron Resistance

A

Revision

Example:

HV

INN

(Innoscience)

700

(700V)

D

(DFN 8*8)

240

(240mΩ)

B

(Revision)

HV

INN

(Innoscience)

700

(700V)

DC

(DFN 5*6(C))

100

(100mΩ)

E

(Revision)

LV

INN

(Innoscience)

040

(40V)

W

(WLCSP)

048

(4.8 mΩ)

A

(Revision)

VGaN

INV

(Innoscience)

100

(100V)

EQ

(EN-FCQFN)

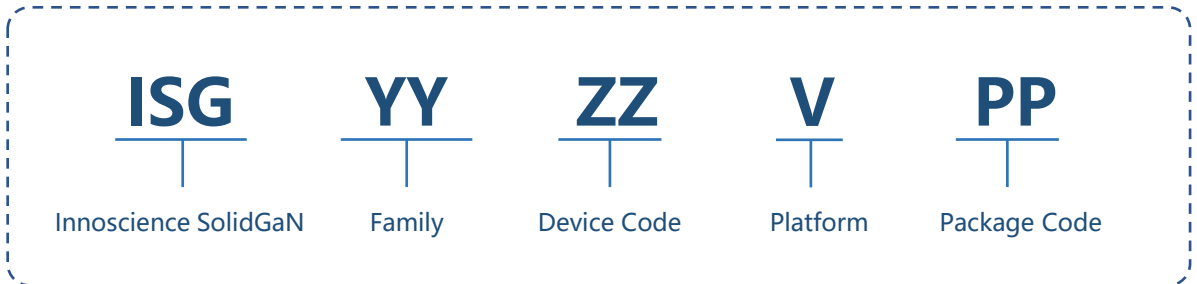
030

(3.0 mΩ)

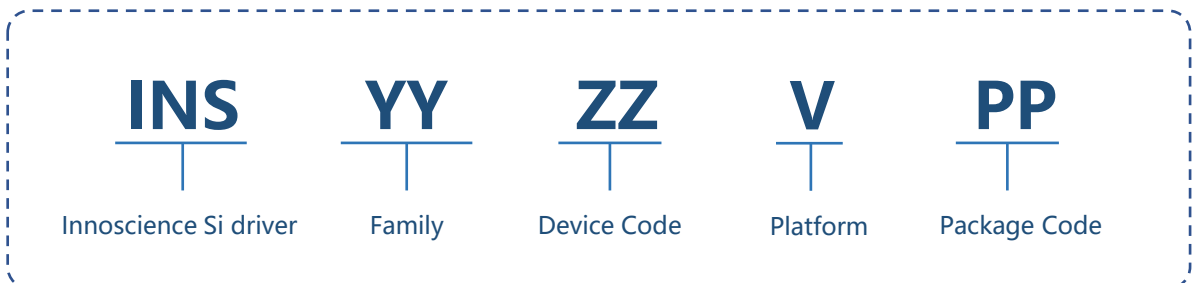
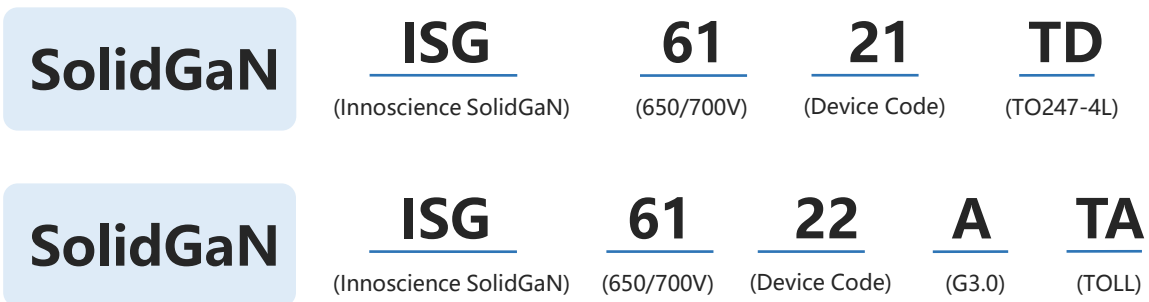
C

(Revision)

SolidGaN & Driver IC



Example:



Example:

